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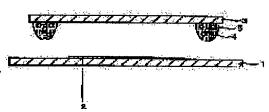
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(54) MANUFACTURE OF ORGANIC EL ELEMENT

(57) Abstract:

PROBLEM TO BE SOLVED: To improve sealing failures, minimize influence of an outside air or water or the like, lessen deterioration during an elapse of time, and ensure long service life by disposing a s aling plate via a sealing bond on a substrate having an organic EL structure laminated, and pressurizing and bonding the sealing plate to the substrate in an atmosphere under a specific pressure. SOLUTION: An organic EL structure 2 is laminated on a substrate 1, and a sealing bond 5 is applied onto a sealing plate 3 in an atmosphere or in a sealing gas atmosphere such as Ar, He, N2 or the like. For example, the sealing bond 5 in which a granular spacer 4 is mixed is applied onto a connection portion of the sealing plate 2. When a region in which the bond of the sealing plate 3 is generally applied, that is, a connection portion is applied so as not to overlap a region in which the organic EL structure 2 is laminated, when at least the sealing plate 3 is disposed. Next, the sealing plate 3 is disposed on the substrate 2 via the sealing bond 5, and the sealing plate 3 is pressurized and bonded to the substrate 1 in an atmosphere of a pressure of 710 to 250 mmHg.



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